

Description

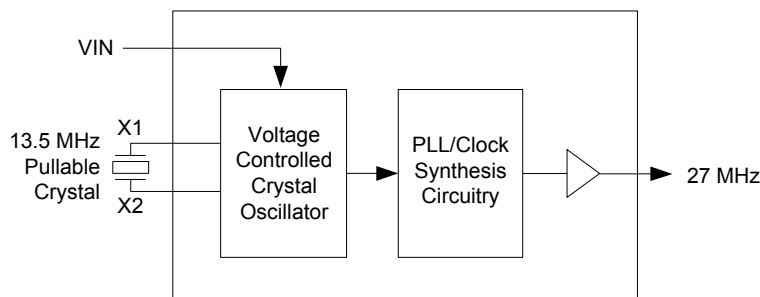
The MK2727 is IDT's lowest cost, low-jitter, high-performance VCXO and PLL clock synthesizer designed to replace expensive 27MHz VCXOs. The on-chip Voltage Controlled Crystal Oscillator accepts a 0 to 3V input voltage to cause the output clocks to vary by ± 100 ppm. Using IDT's patented VCXO and analog Phase-Locked Loop (PLL) techniques, the device uses an inexpensive external 13.5 MHz pullable crystal input to produce a 27 MHz output clock.

IDT manufactures the largest variety of Set-Top Box and multimedia clock synthesizers for all applications. If more clock outputs are needed, see the MK2731 or MK277x family of parts. Consult IDT to eliminate VCXOs, crystals and oscillators from your board.

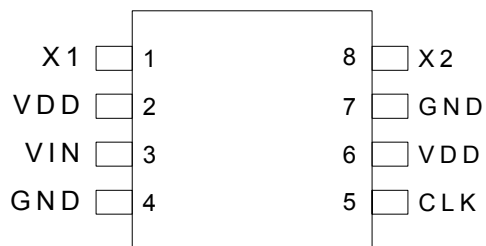
Features

- Packaged in 8-pin narrow SOIC
- Uses an inexpensive 13.500 MHz external crystal
- On-chip VCXO with pull range of 200 ppm (minimum)
- VCXO input tuning voltage 0 to 3.3 V
- 25 mA output drive capability at TTL levels
- Advanced, low-power, sub-micron CMOS process
- 5 V operating voltage

Block Diagram



Pin Assignment



8-Pin (150 mil) SOIC

Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	X1	Input	Crystal connection. Connect to a pullable 13.5 MHz crystal.
2	VDD	Power	Connect to +5 V.
3	VIN	Input	Voltage input to VCXO. Zero to 3 V analog input which controls the frequency of the VCXO.
4	GND	Power	Connect to ground.
5	CLK	Output	27 MHz clock output.
6	VDD	Power	Connect to +5 V.
7	GND	Power	Connect to ground.
8	X2	Input	Crystal connection. Connect to a pullable 13.5 MHz crystal.

External Component Selection

The MK2727 requires a minimum number of external components for proper operation.

Decoupling Capacitor

A decoupling capacitor of 0.01 μ F must be connected between VDD (pin 2) and GND (pin 4), as close to these pins as possible. For optimum device performance, the decoupling capacitor should be mounted on the component side of the PCB. Avoid the use of vias in the decoupling circuit.

Series Termination Resistor

When the PCB trace between the clock output (CLK, pin 5) and the load is over 1 inch, series termination should be used. To series terminate a 50 Ω trace (a commonly used trace impedance), place a 33 Ω resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is 20 Ω .

Quartz Crystal

The MK2727 VCXO function consists of the external crystal and the integrated VCXO oscillator circuit. To assure the best system performance (frequency pull range) and reliability, a crystal device with the recommended parameters (shown below) must be used, and the layout guidelines discussed in the following section shown must be followed.

The frequency of oscillation of a quartz crystal is determined by its “cut” and by the load capacitors connected to it. The MK2727 incorporates on-chip variable load capacitors that “pull” (change) the frequency of the crystal. The crystal

specified for use with the MK2727 is designed to have zero frequency error when the total of on-chip + stray capacitance is 14 pF.

Recommended Crystal Parameters:

Initial Accuracy at 25° C	±20 ppm
Temperature Stability	±30 ppm
Aging	±20 ppm
Load Capacitance	14 pF
Shunt Capacitance, C0	7 pF Max
C0/C1 Ratio	250 Max
Equivalent Series Resistance	35 Ω Max

The external crystal must be connected as close to the chip as possible and should be on the same side of the PCB as the MK2727. There should be no vias between the crystal pins and the X1 and X2 device pins. There should be no signal traces underneath or close to the crystal.

Crystal Tuning Load Capacitors

The crystal traces should include pads for small fixed capacitors, one between X1 and ground, and another between X2 and ground. The need for these capacitors is determined at system prototype evaluation, and is influenced by the particular crystal used (manufacture and frequency) and by PCB layout. The typical required capacitor value is 1 to 4 pF.

The procedure for determining the value of these capacitors can be found in application note MAN05.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the MK2727. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7 V
All Inputs and Outputs	-0.5 V to VDD+0.5 V
Ambient Operating Temperature	0 to +70° C
Storage Temperature	-65 to +150° C
Soldering Temperature	260° C

Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Units
Ambient Operating Temperature	0		+70	° C
Power Supply Voltage (measured in respect to GND)	+4.75	5.0	+5.25	V
Reference crystal parameters	Refer to page 3			

DC Electrical Characteristics

VDD=5 V \pm 5% , Ambient temperature 0 to +70° C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		4.75		5.25	V
Output High Voltage	V _{OH}	I _{OH} = -25 mA	2.4			V
Output Low Voltage	V _{OL}	I _{OL} = 25 mA			0.4	V
Output High Voltage (CMOS Level)	V _{OH}	I _{OH} = -8 mA	VDD-0.4			V
Operating Supply Current	I _{DD}	No load		20		mA
Short Circuit Current	I _{OS}			\pm 100		mA
VIN, VCXO Control Voltage	V _{IA}		0		3	V

AC Electrical Characteristics

VDD = 5 V \pm 5%, Ambient Temperature 0 to +70° C, unless stated otherwise

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Input Crystal Frequency				13.500		MHz
Input Crystal Accuracy					\pm 30	ppm
Output Clock Rise Time	t _{OR}	0.8 to 2.0 V			1.5	ns
Output Clock Fall Time	t _{OF}	2.0 to 0.8 V			1.5	ns
Output Clock Duty Cycle	t _D	Measured at 1.4 V	40	50	60	%
Maximum Absolute Jitter, short term	t _J			200		ps
27 MHz Output Pullability		0V \leq VIN \leq 3 V, Note 1	\pm 100			ppm

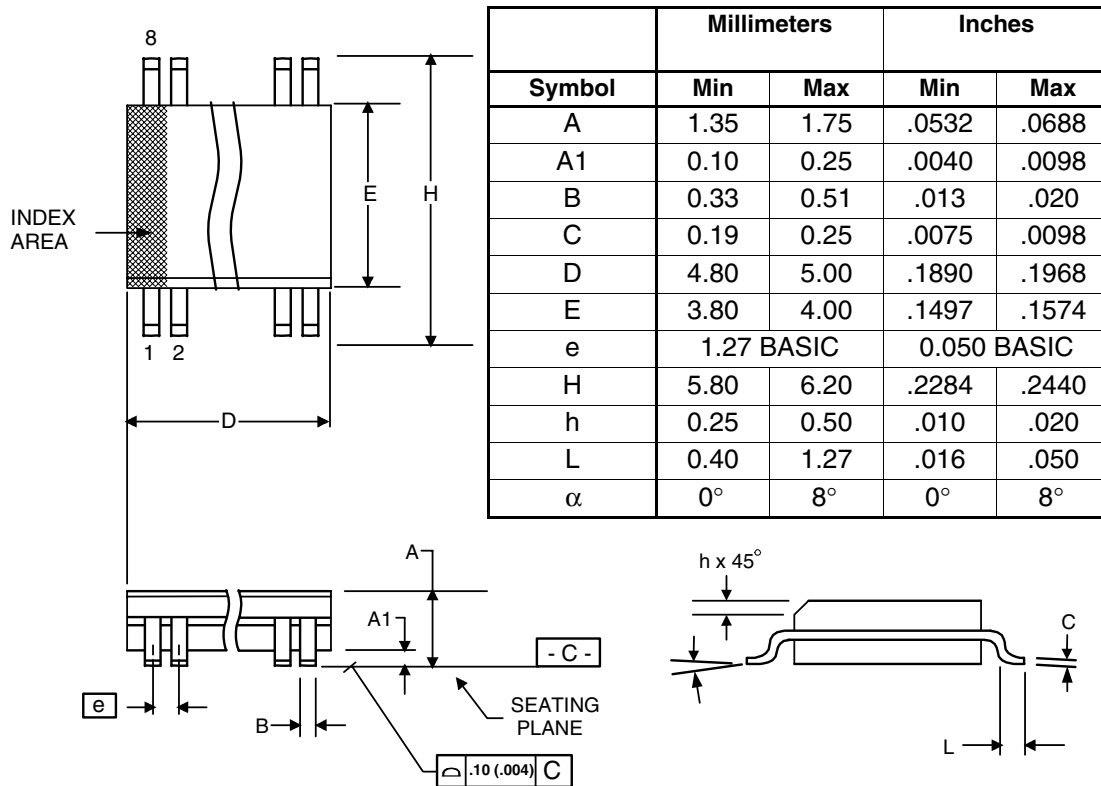
Note 1: External crystal device must conform with Pullable Crystal Specifications listed on page 3.

Thermal Characteristics

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ_{JA}	Still air		150		°C/W
	θ_{JA}	1 m/s air flow		140		°C/W
	θ_{JA}	3 m/s air flow		120		°C/W
Thermal Resistance Junction to Case	θ_{JC}			40		°C/W

Package Outline and Package Dimensions (8-pin SOIC, 150 Mil. Narrow Body)

Package dimensions are kept current with JEDEC Publication No. 95



Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
MK2727SLF	2727SL	Tubes	8-pin SOIC	0 to +70° C
MK2727SLFTR	2727SL	Tape and Reel	8-pin SOIC	0 to +70° C

“LF” denotes Pb (lead) free package.

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Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,
Koto-ku, Tokyo 135-0061, Japan
www.renesas.com

Contact Information

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